504548781 09/14/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4595489

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MINGZHU WANG	08/24/2017
BOJIE ZHAO	08/23/2017
ZHENYU CHEN	08/23/2017
TAKEHIKO TANAKA	08/24/2017
NAN GUO	08/24/2017
ZHEN HUANG	08/24/2017
DUANLIANG CHENG	08/24/2017
LIANG DING	08/23/2017
FEIFAN CHEN	08/23/2017
HENG JIANG	08/25/2017

RECEIVING PARTY DATA

Name:	NINGBO SUNNY OPOTECH CO., LTD.
Street Address:	66-68, SHUNYU ROAD, YUYAO CITY,
City:	NINGBO, ZHEJIANG
State/Country:	CHINA
Postal Code:	315400

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15460216

CORRESPONDENCE DATA

Fax Number: (626)571-9813

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 626-571-9812

Email: RAYMONDC@DAVIDANDRAYMOND.COM
Correspondent Name: DAVID AND RAYMOND PATENT FIRM

Address Line 1: 108 N. YNEZ AVE., SUITE 128

Address Line 4: MONTEREY PARK, CALIFORNIA 91754

ATTORNEY DOCKET NUMBER: USCP10130C/NB2926-SYO

PATENT REEL: 043598 FRAME: 0091

504548781

NAME OF CURNITTER	MOUAELLEE
NAME OF SUBMITTER:	MICHAEL LEE
SIGNATURE:	/Michael Lee/
DATE SIGNED:	09/14/2017
Total Attachments: 10	
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Attorney's

Docket No.: USCP10130C/NB2926-SYO

ASSIGNMENT

whose post of	fice address(es)		hereinafter	referred to	o as ASSIGNO	OR, have invented a
certain new and	d useful improve	ments in				
Array Imaging	Module and Mo	olded Photosensiti	ve Assembly	, Circuit B	loard Assembly	and Manufacturing
, , ,	of for Electronic				·	
(hereinafter ref	erred to as the IN	VENTION) for wi	hich an appli	cation for (United States L	etters Patent was
	executed on eve	n data herewith				
	executed on:					
$\overline{\boxtimes}$	filed on: 03/1:	5/2017	Se	rial No.:	15/460,216	
B236	3310 G 5311 V 2/11	P:				

WHEREAS, Ningbo Sunny Opotech Co., Ltd. whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400 hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States:

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument, ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof, and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Mingzhu Wang

ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

Attorney's

Docket No. USCP10130C/NB2926-SYO

ASSIGNMENT

whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a

WHEREAS, I (we), Bojie Zhao

certain new and useful improvements in Array Imaging Module and Its Molded Photosensitive Assembly, Circuit Board Assembly, and Manufacturing Methods Thereof for Electronic Device (hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was executed on even data herewith executed on: filed on: 03/15/2017 Serial No.: 15/460,216
WHEREAS, Ningbo Sunny Opotech Co.,Ltd. whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400 hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;
NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.
ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.
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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.
ASSIGNOR NAME: Bojie Zhao ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400
Bolie 2hos 2017. 8.23
SIGNATURE) DATE

Attorney's Docket No.. USCP10130C/NB2926-SYO

ASSIGNMENT

whose post office addrecertain new and useful in Array Imaging Module a Methods Thereof for Electhereinafter referred to as executed executed executed	nprovements in and Molded Photosensitive Assoctronic Device is the INVENTION) for which an on even data herewith	embly, Circuit Bo	
whose post office address	Ningbo Sunny Opotech Co.,Ltd s is 66-68 Shunyu Road,Yuyao ASSIGNEE, is desirous of acqu	l, City,Ningbo,Zheji	
acknowledged, I (we), A entire right, title, and into	SSIGNOR, by these presents do erest in and to said INVENTIO and all Letters Patent granted of	sell, assign and N and application	n, receipt of which is hereby transfer unto said ASSIGNEE, the n throughout the United States of continuation, continuation-in-part
connection with the fil application(s) in the Un required to affirm the rig ASSIGNOR also agrees, communicate to ASSIGNE that are within ASSIGNO behalf of ASSIGNEE that and defense of any pat	ling, prosecution and mainter ited States for said INVENTIO ghts of ASSIGNEE in and to sa without further consideration EE at ASSIGNEE'S request docu DR'S possession or control, and lawfully may be required of AS- tent application or patent end under this instrument shall exte	nance of said a DN, including ad sid INVENTION, a and at ASSIGI ments and inform d to provide furt SIGNOR in respect compassed within	that legally may be required in application or any other patent iditional documents that may be all without further consideration. NEE'S expense, to identify and nation concerning the INVENTION her assurances and testimony on the of the prosecution, maintenance in the terms of this instrument. 'S heirs, executors, administrators
issue any and all Letters I and interest in and to the ASSIGNEE'S legal represe	Patent referred to above to ASS e same, for ASSIGNEE'S sole entatives and successors, to the	SIGNEE, as the A use and behoof full end of the te	oner of Patents and Trademarks to SSIGNEE of the entire right, title ; and for the use and behoof of erm for which such Letters Patent y ASSIGNOR had this assignment
	norizes Raymond Y. Chan to in al in the U.S. Patent and Trader		any information in this document
	enyu Chen ou Road, Yuyao City, Ningbo, Zhejia	ng Province,China	315400
Zhenyu Chen		20	17.08.23
SIGNATURE		DAT	E

LITHLITY PATENT

Attorney's

Docket No USCP10130CNB2926-SYO

ASSIGNMENT

WHEREAS, I (we), Takehiko Tanaka

whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in

Array Imaging Module and Molded Photosensitive Assembly, Circuit Board Assembly and Manufacturing Methods Thereof for Electronic Device

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was executed on even data herewith

executed on:

filed on: 03/15/2017

Serial No.:

15/460.216

WHEREAS, Ningbo Sunny Opotech Co., Ltd.

whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400 hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States:

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Takehiko Tanaka

ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

Edniko Tahaka 2017.8.24

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Attorney's

Docket No.: USCP10130C/NB2926-SYO

ASSIGNMENT

WHE	EREAS, I (we),	Nan Guo				
whose post of	ffice address(es) appear(s)	below, her	einafter referred t	o as ASSIGNOR	R, have invented a
certain new an	id useful improv	ements in				
Array Imaging	Module and M	folded Photo	sensitive A	ssembly, Circuit E	Board Assembly	and Manufacturing
	eof for Electron			•		
hereinafter re	ferred to as the	INVENTION) for which	an application for	United States Le	tters Patent was
	executed on ex					
Ħ	executed on:					
\boxtimes	filed on: 03/	15/2017		Serial No.:	15/460,216	
WHE	EREAS, Ning	bo Sunny Og	otech Co.,I	_td.		

whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400 hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ADDRESS:	NAME: Nan Guo 66-68 Shunyu Road, Yuyao City, Ningbo, Zi	hejlang Province,China 315400	
	NAN Crub	20TJ. 8. 34	
SIGNATU	RE	DATE	

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Docket No.: USCP10130C/NB2926-SYO

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	HEREAS, I (we), Zhen H			
whose post	office address(es) appear(s	s) below, hereinafter referred	I to as ASSIGNOR, ha	ive invented a
	and useful improvements in		•	
		otosensitive Assembly, Circui	t Roard Assembly and	Manufacturina
and the second	ille mercenia comi mercenzi i ce		I CANGER OF LANSANTREAST A SERVE	SASPERCES PROCESSES
Marchada The	const tien Membrane, transfer	•	٠.	-
	ereof for Electronic Device		•	
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(hereinafter i		N) for which an application fo	•	-
(hereinafter i	referred to as the INVENTIO executed on even data he	N) for which an application fo	•	-
	referred to as the INVENTIO	N) for which an application fo	or United States Letters	

WHEREAS, Ningbo Sunny Opotech Co., Ltd.
whose post office address is 60-68 Shunyu Rond, Yuyao City, Ningbo, Zhejiang Province, China 315400
hereinafter referred to as ASSIGNEE, is desirous of acquiring the online right, title and interest in and to the same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Zhen Huang

ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

Zhan ituarg 2017/8/24
SIGNATURE DATE

Attorney's Docket No: USCP10130C/NB2926-SYO

ASSIGNMENT

A 447-64-64-64-64-64-64-64-64-64-64-64-64-64-
WHEREAS, I (we), Duanliang Cheng whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in Array Imaging Module and Its Molded Photosensitive Assembly, Circuit Board Assembly, and Manufacturing Methods Thereof for Electronic Device (hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was executed on even data herewith executed on: Serial No.: 15/460,216
WHEREAS, Ningbo Sunny Opotech Co.,Ltd. whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400 hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;
NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.
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ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.
ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.
ASSIGNOR NAME: Duanliang Cheng ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400
Dorling Chang Date Date

Attorney's

Docket No.: USCP10130C/NB2926-SYO

ASSIGNMENT

WHEREAS, I (we), Liang Ding

whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain new and useful improvements in

Array Imaging Module and Molded Photosensitive Assembly, Circuit Board Assembly and Manufacturing Methods Thereof for Electronic Device

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even data herewith executed on:

filed on: 03/15/2017

Serial No.: 15/460,216

WHEREAS, Ningbo Sunny Opotech Co., Ltd.

whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400 hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States:

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application.

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ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Liang Ding

ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

SIGNATURE

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Attorney's

Docket No. USCP10130C/NB2926-SYO

ASSIGNMENT

whose post office addr certain new and useful in Array Imaging Modul Manufacturing Methods (hereinafter referred to a executed executed	e and its Molded Photoser Thereof for Electronic Device is the INVENTION) for which are on even data herewith	sitive Assembly,	Circuit Board	Assembly, and
whose post office addres	Ningbo Sunny Opotech Co.,Lt is is 66-68 Shunyu Road,Yuya is ASSIGNEE, is desirous of acq s;	o City,Ningbo,Zhejian		
acknowledged, I (we), A entire right, title, and in	EFORE, for good and valuASSIGNOR, by these presents deterest in and to said INVENTICA and all Letters Patent granted cation.	o sell, assign and tr ON and application	ansfer unto said throughout the I	ASSIGNEE, the United States of
connection with the fi application(s) in the Un required to affirm the ri ASSIGNOR also agrees communicate to ASSIGN that are within ASSIGN pehalf of ASSIGNEE that and defense of any pa	NOR hereby agrees to execute iling, prosecution and maintanited States for said INVENTIGHTS of ASSIGNEE in and to so, without further consideration EE at ASSIGNEE'S request doc OR'S possession or control, at lawfully may be required of Astent application or patent er a under this instrument shall extatives.	enance of said ap iON, including addi- iaid INVENTION, al- on and at ASSIGNI turnents and informat ad to provide further assignor in respect accompassed within	plication or an itional document II without further EE'S expense, to concerning the assurances and of the prosecution the terms of the prosecution.	y other patent its that may be r consideration. to identify and the INVENTION d testimony on on, maintenance his instrument.
ssue any and all Letters and interest in and to the ASSIGNEE'S legal repres	OR hereby authorizes and reque Patent referred to above to AS he same, for ASSIGNEE'S solu- tentatives and successors, to the and entirely as the same would	SIGNEE, as the ASS e use and behoof; e full end of the tern	SIGNEE of the e and for the use m for which such	ntire right, title and behoof of Letters Patent
	horizes Raymond Y. Chan to it dal in the U.S. Patent and Trade		y information in	this document
	ifan Chen yu Road,Yuyao City,Ningbo,Zheji	ang Province,China 3	15400	
Fei fan	n chen		2017.8.2	<u> </u>
SIGNATURE		DATE		

Attorney's

Docket No.: USCP10130C/NB2926-SYO

ASSIGNMENT

WHEREAS, I (we), Heng Jiang
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a certain
new and useful improvements in
Array Imaging Module and Molded Photosensitive Assembly, Circuit Board Assembly and Manufacturing
Methods Thereof for Electronic Device
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was
executed on even data herewith
executed on:

| Serial No.: 15/460,216

WHEREAS. Ningbo Sunny Opotech Co., Ltd.

whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400 hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;

NOW. THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all Letters Patent granted on any division, continuation, continuation-in-part and ressue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR bereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behoof, and for the use and behoof of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document needed to effect its recordal in the U.S. Patent and Trademark Office.

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Heng Jiang 2017. 8.25

SIGNATURE DATE

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